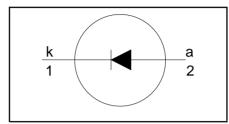
BY229F, BY229X series

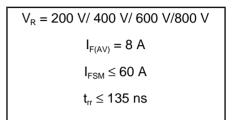
FEATURES

- Low forward volt drop
- Fast switching
- Soft recovery characteristic
- High thermal cycling performance
 Isolated mounting tab

SYMBOL



QUICK REFERENCE DATA



GENERAL DESCRIPTION

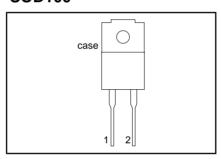
Glass-passivated double diffused rectifier diodes featuring low forward voltage drop, fast reverse recovery and soft recovery characteristic. The devices are intended for use in TV receivers, monitors and switched mode power supplies.

The BY229F series is supplied in the conventional leaded SOD100 package. The BY229X series is supplied in the conventional leaded SOD113 package.

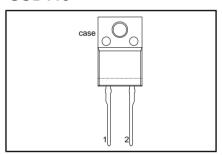
PINNING

DESCRIPTION		
cathode		
anode		
isolated		

SOD100



SOD113



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	. MAX.		UNIT		
V_{RSM}	Peak non-repetitive reverse	BY229F- / BY229X-	-	200 200	400 400	600 600	800 800	V
V _{RRM} V _{RWM} V _R	voltage Peak repetitive reverse voltage Crest working reverse voltage Continuous reverse voltage		- - -	200 150 150	400 300 300	600 500 500	800 600 600	V V V
I _{F(AV)}	Average forward current ¹	square wave; $\delta = 0.5$; $T_{hs} \le 83 ^{\circ}C$	-	8		Α		
		$T_{hs} = 0.5$ C sinusoidal; $a = 1.57$; $T_{hs} \le 90$ °C	-		7	7		А
I _{F(RMS)}	RMS forward current	I hs = 50 0	_		1	1		Α
I _{FRM}	Peak repetitive forward current	$t = 25 \mu s; \delta = 0.5;$ $T_{hs} \le 83 ^{\circ} C$	-		1	6		А
I _{FSM}	Peak non-repetitive forward	t = 10 ms	-		_	0		Α
	current	t = 8.3 ms sinusoidal; $T_j = 150 ^{\circ}\text{C}$ prior to surge; with	-		6	6		A
l ² t	I ² t for fusing	reapplied V _{RWM(max)} t = 10 ms	_		1	8		A ² s
T _{stg}	Storage temperature		-40			l °C ∣		
T _j	Operating junction temperature		-	150		°C		

^{1.} Neglecting switching and reverse current losses.

Philips Semiconductors Product specification

Rectifier diodes fast, soft-recovery

BY229F, BY229X series

ISOLATION LIMITING VALUE & CHARACTERISTIC

 T_{hs} = 25 °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{isol}	Peak isolation voltage from both terminals to external heatsink	SOD100 package; R.H. ≤ 65%; clean and dustfree	ı	1	1500	V
V _{isol}	R.M.S. isolation voltage from both terminals to external heatsink	SOD113 package; f = 50-60 Hz; sinusoidal waveform; R.H. ≤ 65%; clean and dustfree	-	-	2500	V
C _{isol}	Capacitance from pin 1 to external heatsink	f = 1 MHz	-	10	-	pF

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{\text{th } j\text{-hs}}$ $R_{\text{th } j\text{-a}}$	heatsink	with heatsink compound without heatsink compound in free air.		- - 55	4.8 7.2 -	K/W K/W K/W

STATIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

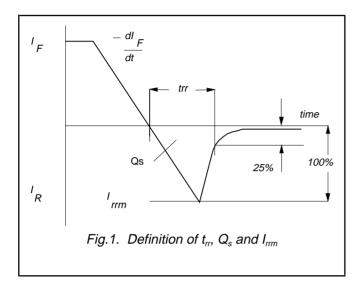
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{F}	Forward voltage	I _F = 20 A	-	1.5	1.85	V
l _R	Reverse current	$V_{R} = V_{RWM}; T_{i} = 125 ^{\circ}C$	-	0.1	0.4	mA

DYNAMIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$d_{\rm R}$	Reverse recovery charge	$\begin{array}{l} I_F = 1 \text{ A; } V_R \geq 30 \text{ V; } -dI_F/dt = 50 \text{ A/}\mu\text{s} \\ I_F = 2 \text{ A; } V_R \geq 30 \text{ V; } -dI_F/dt = 20 \text{ A/}\mu\text{s} \\ I_F = 2 \text{ A; } -dI_F/dt = 20 \text{ A/}\mu\text{s} \end{array}$		100 0.5 50	135 0.7 60	ns μC A/μs

BY229F, BY229X series



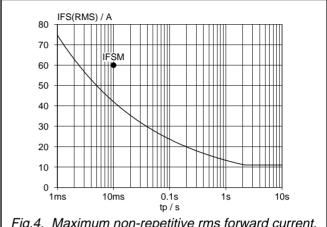


Fig.4. Maximum non-repetitive rms forward current. $I_F = f(t_p)$; sinusoidal current waveform; $T_j = 150^{\circ} C$ prior to surge with reapplied V_{RWM} .

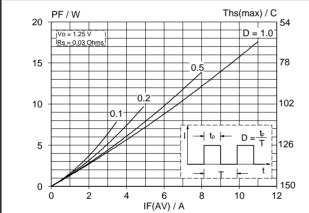


Fig.2. Maximum forward dissipation, $P_F = f(I_{F(AV)})$; square wave current waveform; parameter D = duty $cycle = t_p/T$.

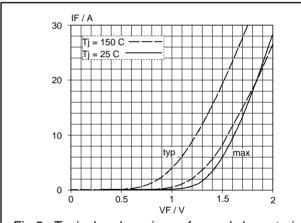


Fig.5. Typical and maximum forward characteristic; $I_F = f(V_F)$; parameter T_i

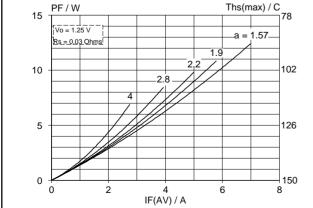
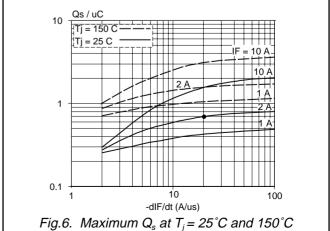
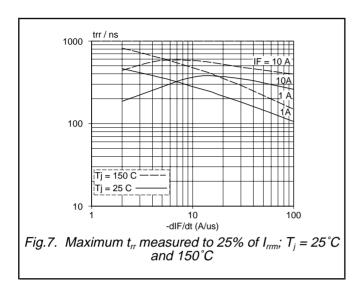
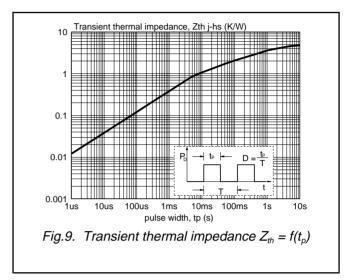


Fig.3. Maximum forward dissipation, $P_F = f(I_{F(AV)})$; sinusoidal current waveform; parameter a = form factor $= I_{F(RMS)}/I_{F(AV)}$.



BY229F, BY229X series





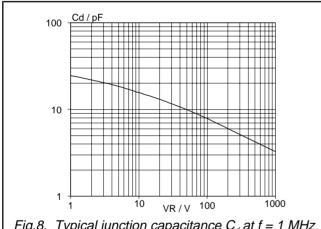
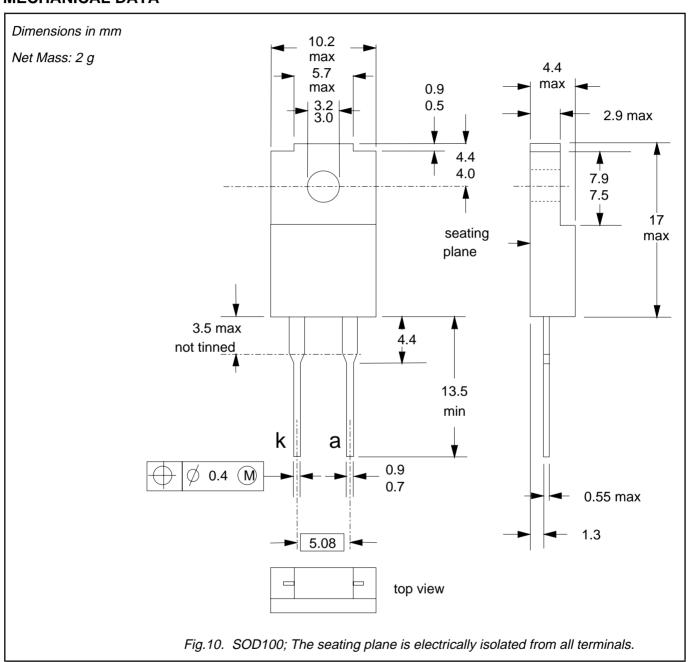


Fig.8. Typical junction capacitance C_d at f = 1 MHz, $T_j = 25^{\circ}C$

BY229F, BY229X series

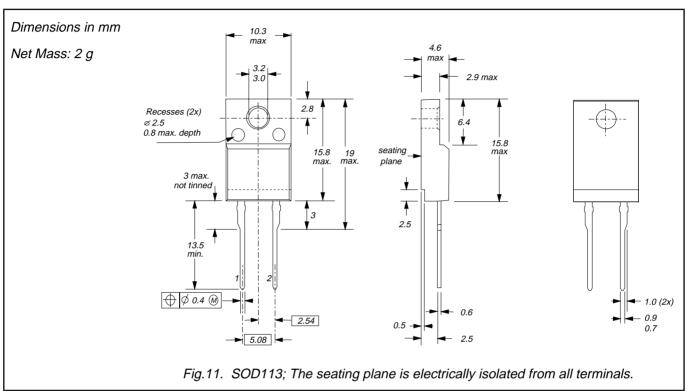
MECHANICAL DATA



- Refer to mounting instructions for F-pack envelopes.
 Epoxy meets UL94 V0 at 1/8".

BY229F, BY229X series

MECHANICAL DATA



Notes

- Refer to mounting instructions for F-pack envelopes.
 Epoxy meets UL94 V0 at 1/8".

Philips Semiconductors Product specification

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DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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